

2019 IEEE INTERNATIONAL SYMPOSIUM ON ELECTROMAGNETIC COMPATIBILITY, SIGNAL & POWER INTEGRITY





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NEW ORLEANS, LOUISIANA

2019
JULY 22-26

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Detecting Latch-up Soft Failure Using an On-Die Sensor and Linux Kernel Log

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Outline

- Why is the Soft Failure Susceptibility relevant?
- The characterization process:
 - High-level overview
 - Injection / measurement setup (hardware)
 - Automation algorithm (software)
- Detection of latch-up:
 - Use existing sub-systems to detect failure
- Moving forward: what was learned?



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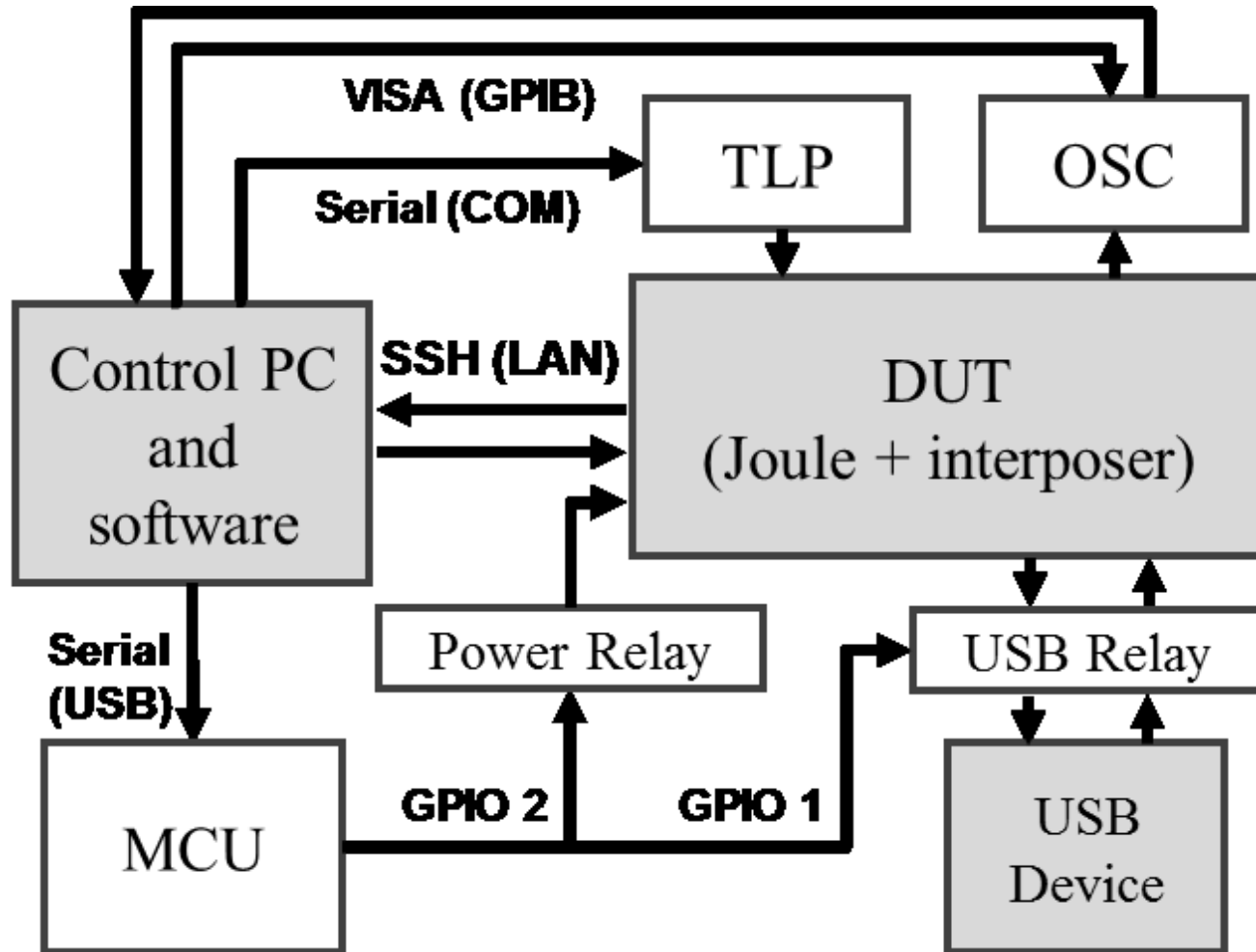
- **Soft Failures (SF)** cause device malfunction, loss of data, etc.
- Many factors affect whether fail occurs:
1) hardware 2) software 3) system state
- Failure occurrence is statistical by nature → 100s of tests needed



- Benefits of SF characterization:
 - **“Getting it right the first time”** - less time in development
 - **Less man-hours spent** - automation saves time
 - **Transferrable to other interfaces** with little change
 - **Risk management** - better understanding of the system



Characterization system setup

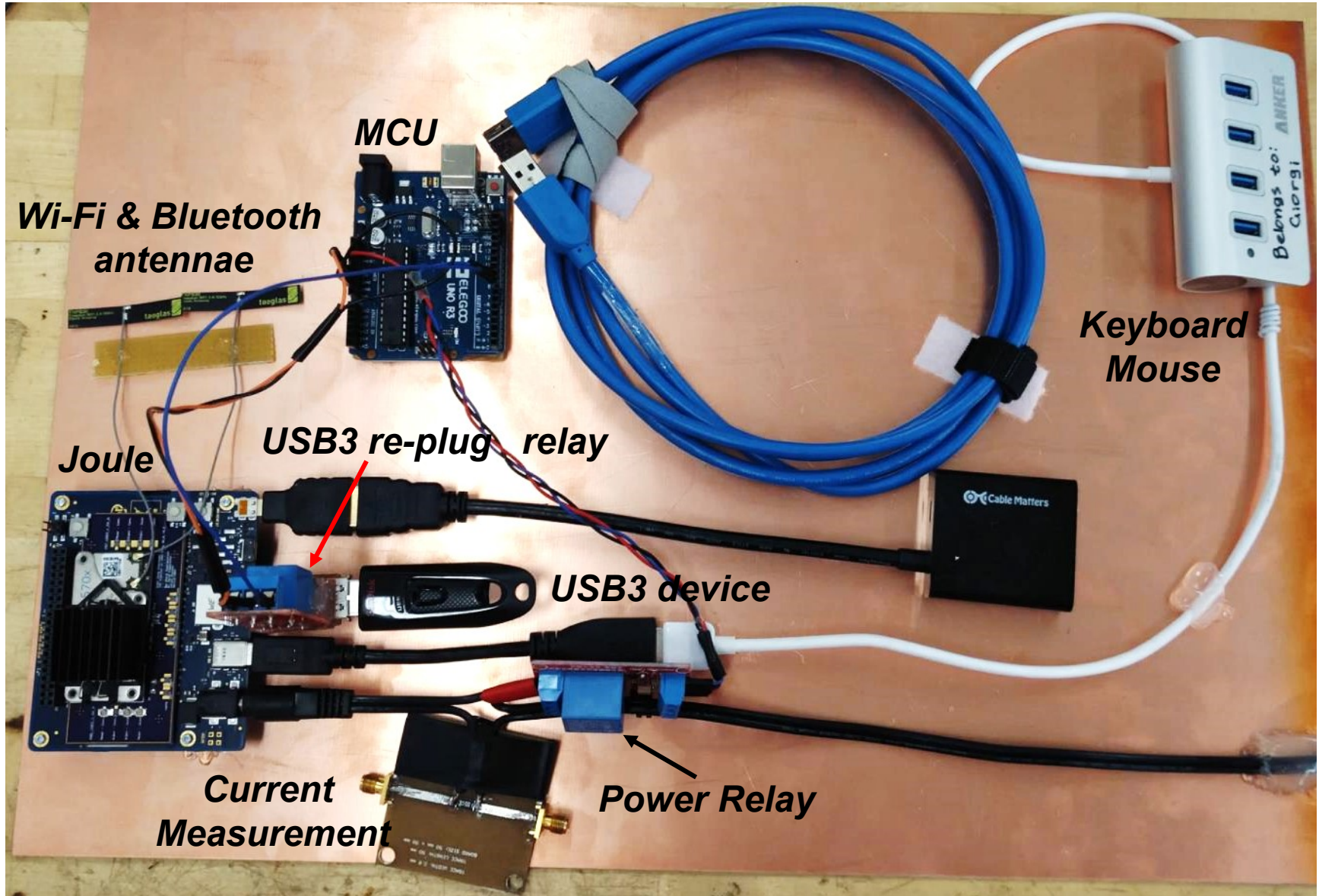




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The dev platform (DUT) in 2 parts:

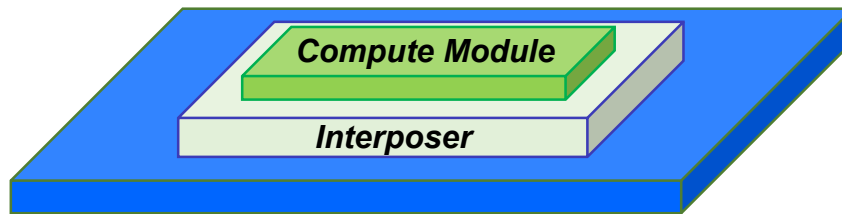
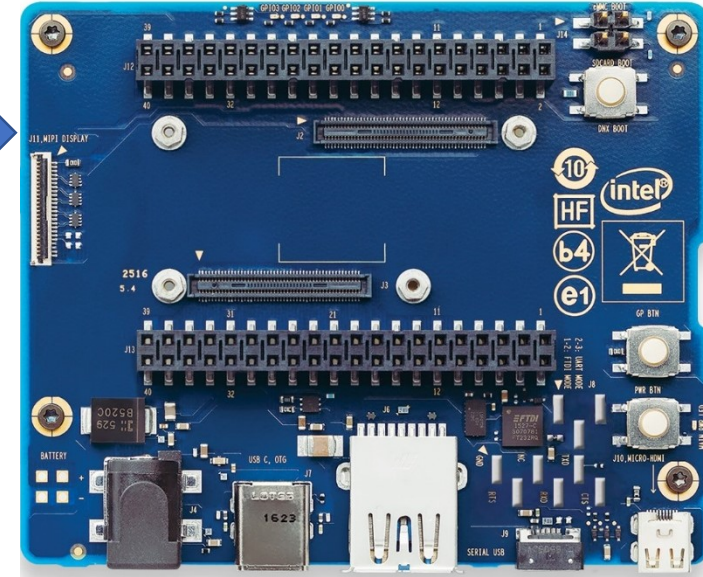
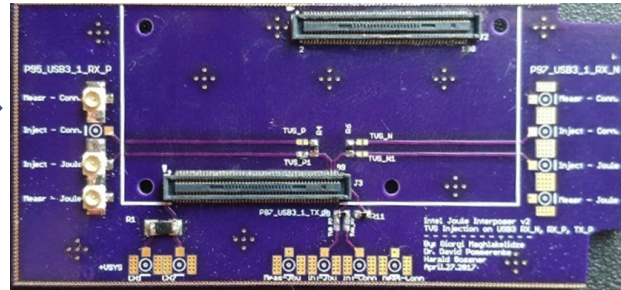
Compute module – all main ICs (CPU, RAM, eMMC, Bluetooth, WiFi)

Expansion board – power, fanout (HDMI, microSD, USB3, USB-C, GPIO)

Compute Module

Interposer

Expansion Board



Expansion Board

An **interposer** goes between the boards.

Stress injection directly into the **data** pins of **active interface**.

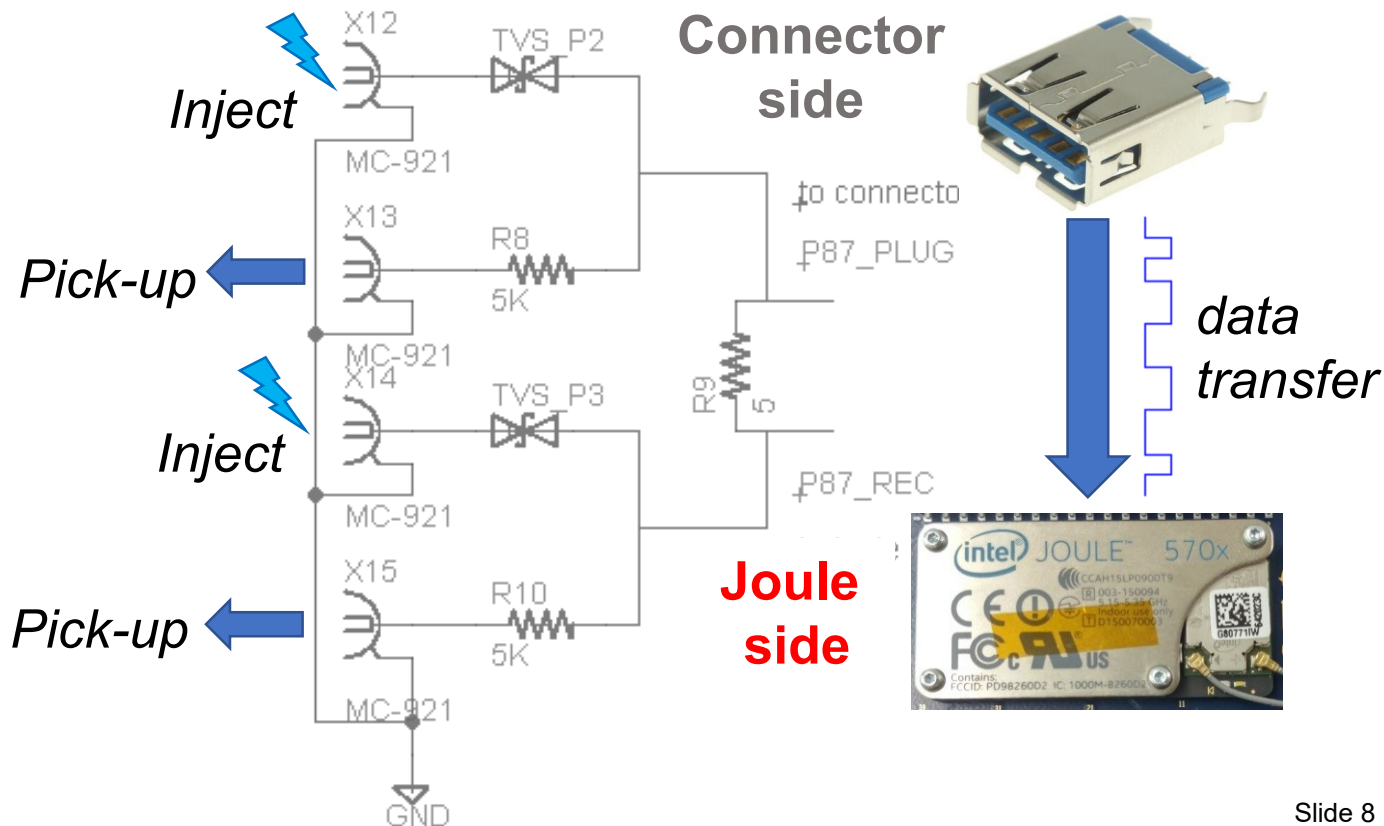
Not introducing SI problems (**TVS injection method** [6]).



Injection at either side of 5Ω resistor (for directionality).

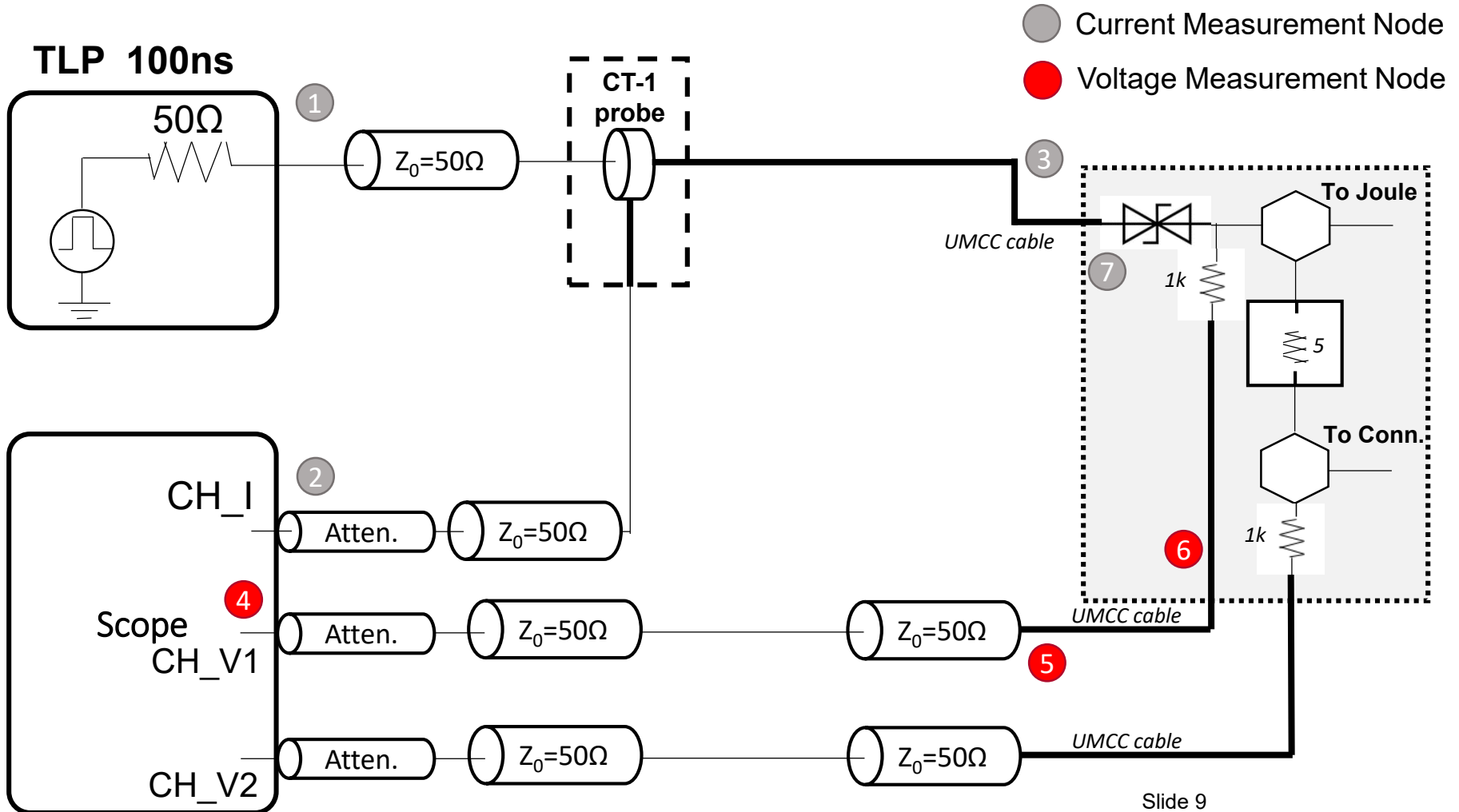
Coax access → UMCC connectors (surface mount snap-in coax).

ESD injection & voltage measurement



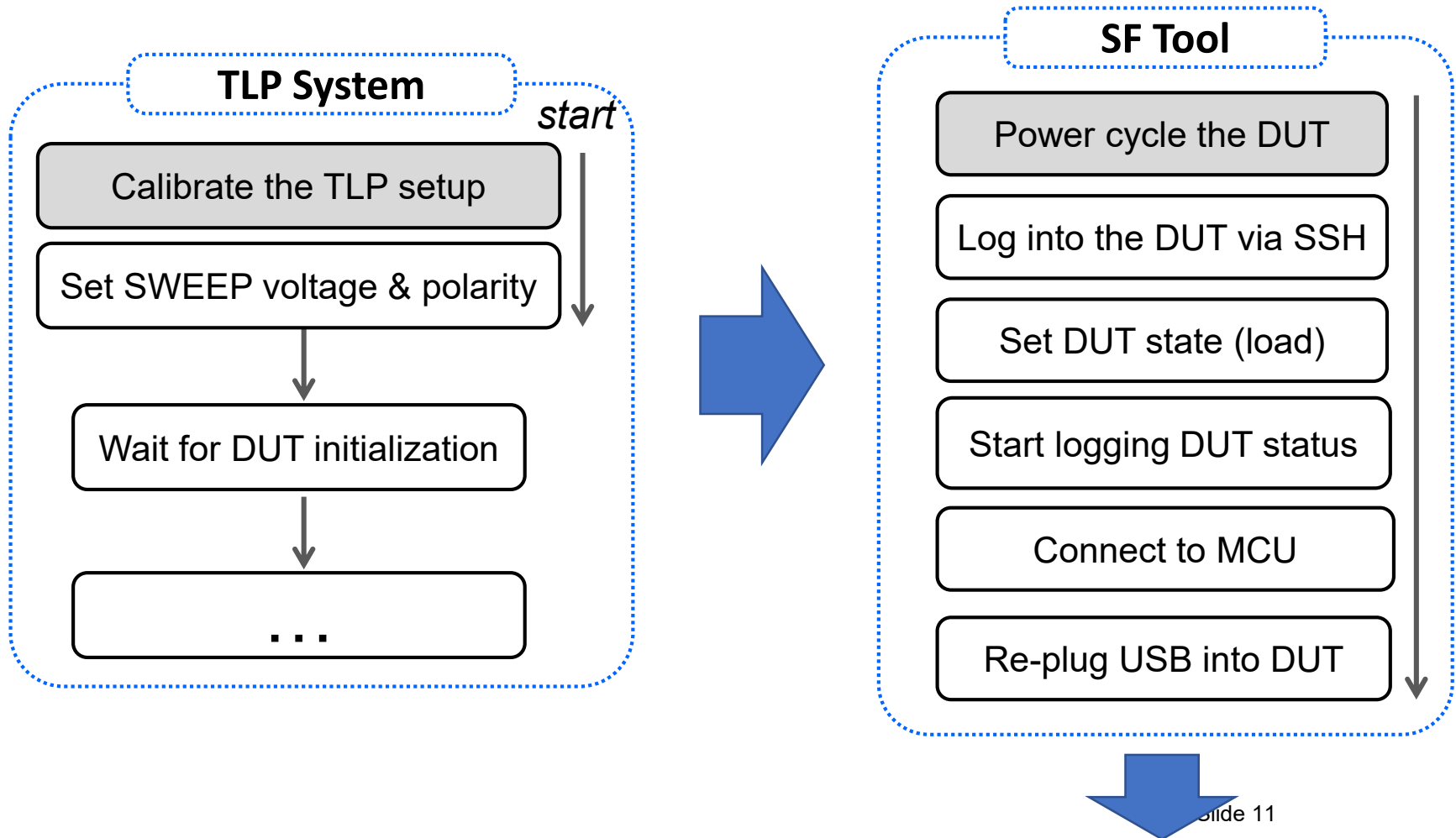


Stress injection setup - 100ns pulse



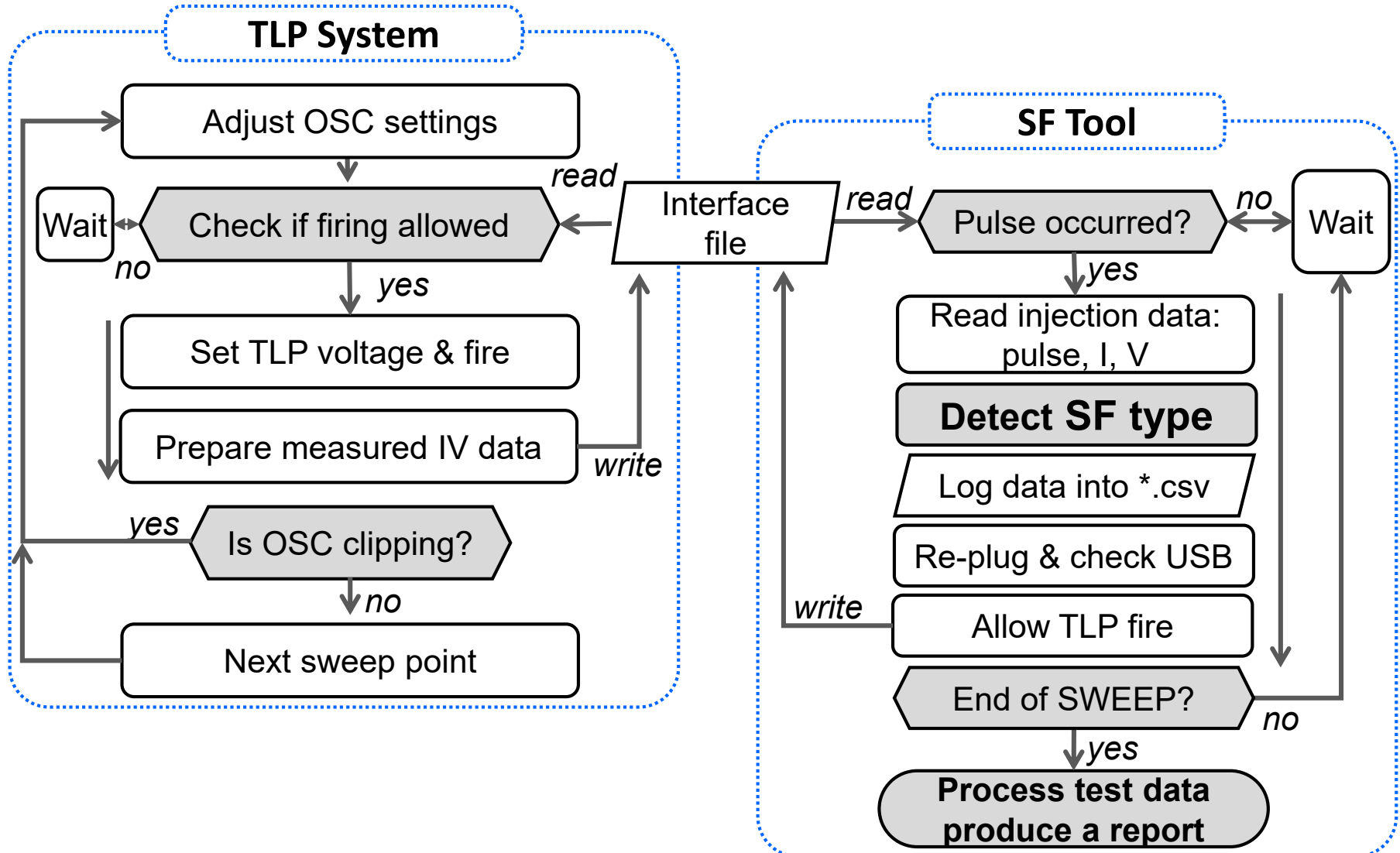


TLP System and DUT initialization:





Fully Automatic USB3 characterization flow





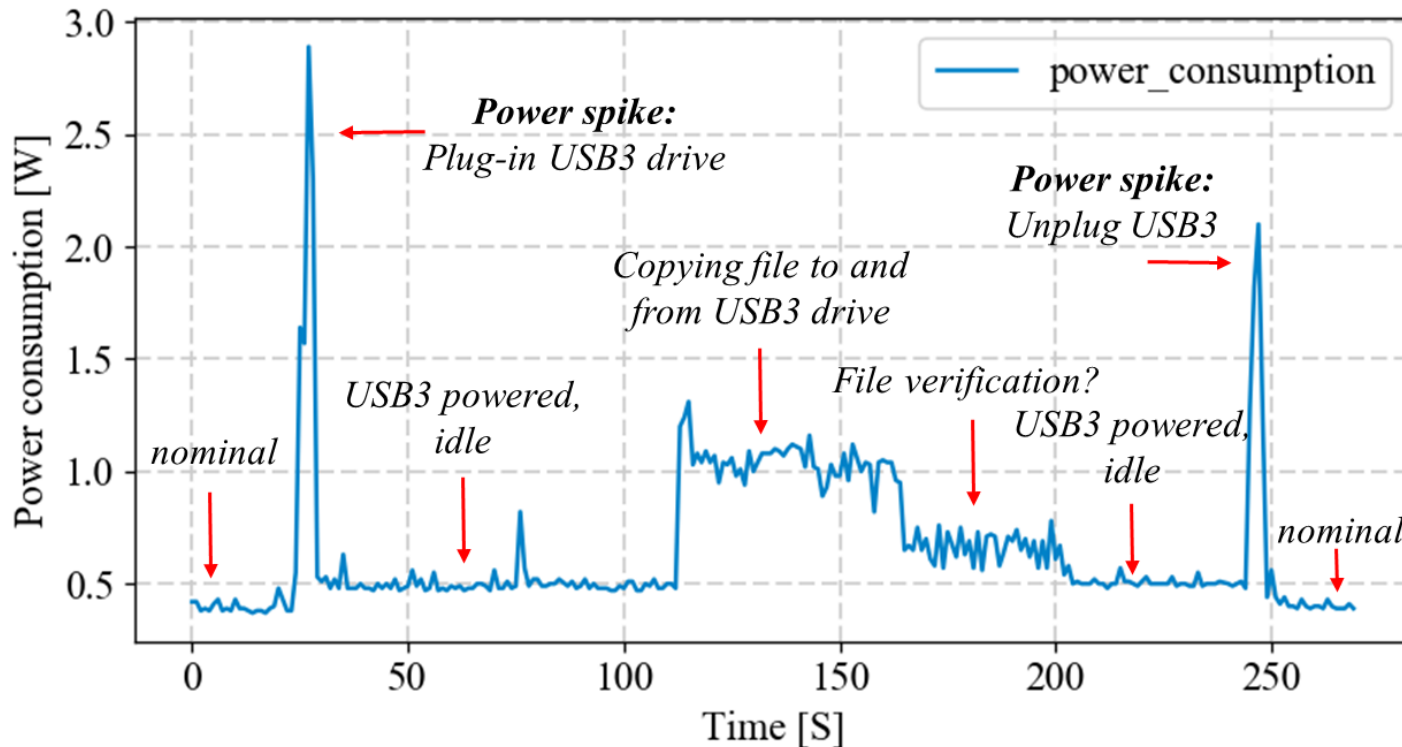
Monitoring DUT power consumption

The Run-time Average Power Limit (RAPL) sub-system of the Intel Joule CPU adjusts processor power to maintain temperature targets.

RAPL reports “energy spent by the processor in micro Joules”. The sensor polled with 1 sec interval at:

```
/sys/class/powercap/intel-rapl/intel-rapl:0/energy_uj
```

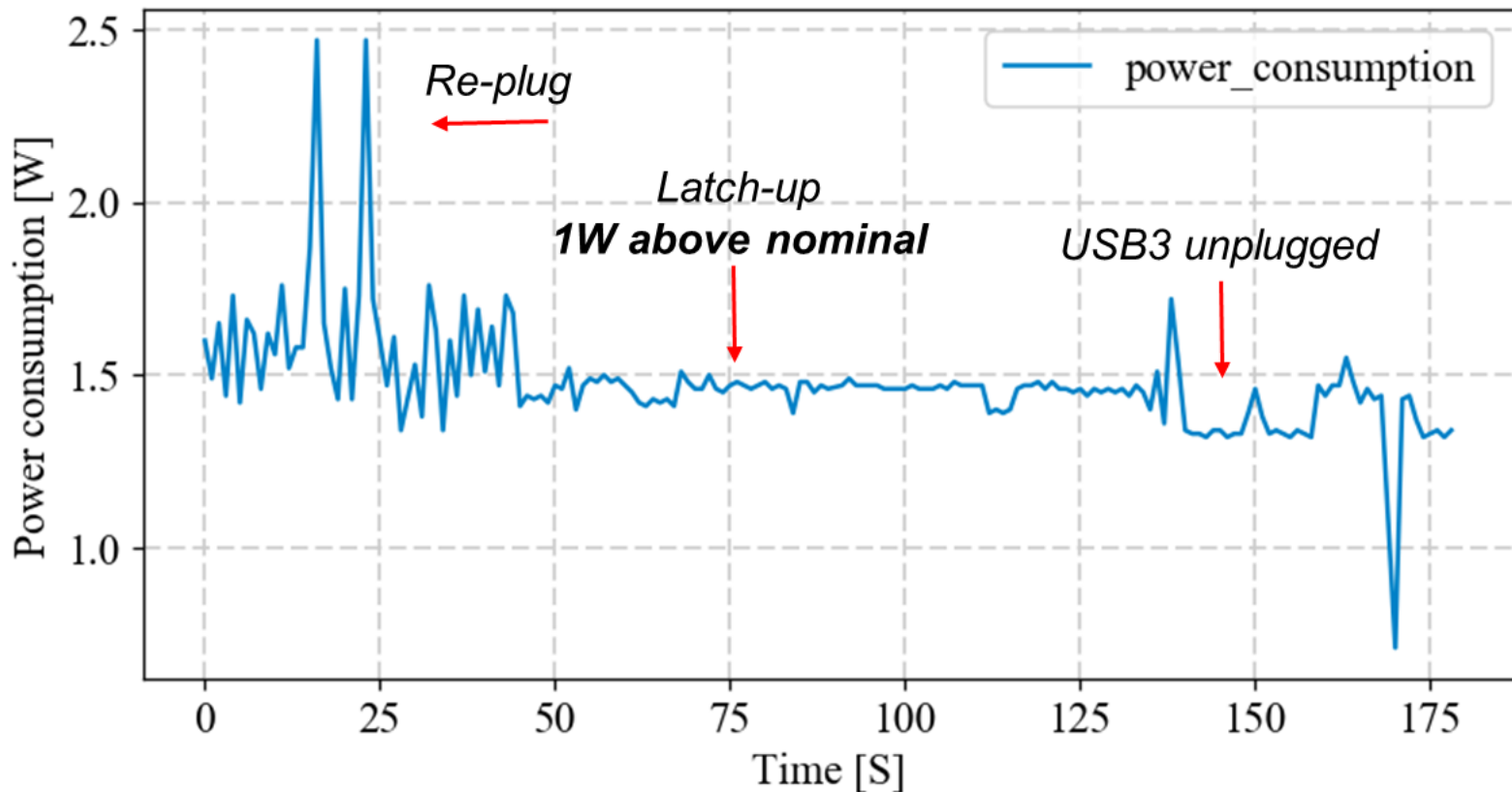
$$P_{avg} = \frac{E(t_2) - E(t_1)}{t_2 - t_1}$$





Power consumption due to Latch-up

Occurs when USB3 device is plugged in. Cannot resolve without full power cycle.
Detected without needing any external instruments.





Cat.	Visible	Interact	Example for USB
A	X	X	Bit errors; packets getting resent
B	✓	X	Drop in data throughput; connection re-established by host
C	✓	✓	Stop of data transfer; re-plugging or power cycling required
D	X	✓	Latch-up (power drain)

Mode	Cat.	Symptoms	Auto-resolve	Re-plug	Re-boot	Power Cycle
1	B	Drop in the data rate	✓	-	-	-
2.1	B	Client re-enumerated in USB3 mode; restored by the system	✓	-	-	-
2.2	B	Client re-enumerated in USB3 mode; GUI pop-up message appears	~	-	-	-
3	C	Client device falls back to USB2 mode	X	✓	✓	✓
4	C	Client device disappears	X	✓	✓	✓
5	D	Persistent power drain (latchup)	X	X	X	✓
6	C	Wi-Fi functionality is lost	X	X	X	✓



Conclusions

- Sometimes existing sub-systems can be used to our advantage.
- Latch-up is one of the most vicious Soft Failures for embedded and battery-powered systems.
- Automated test setups help save time and characterize DUTs for SF susceptibility



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Fin.

Thank you for your time!